

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Won-Kwon LEE	10/30/2009
RECEIVING PARTY DATA	
Name:	MagnaChip Semiconductor, Ltd.
Street Address:	1 Hyangjeong-dong, Heungduk-gu, Cheongju-si
City:	Chungcheongbuk-do
State/Country:	REPUBLIC OF KOREA
Postal Code:	361-725
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12619125
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NAME OF SUBMITTER:	Robert J. Goodell
Total Attachments: 1 source=065542-5091_ASSGN#page1.tif	

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PATENT
REEL: 023522 FRAME: 0699

ASSIGNMENT

WHEREAS I/We, the below named inventor(s), [hereinafter referred to as Assignor(s)], have made an invention entitled:

METHOD FOR FORMING DEEP TRENCH IN SEMICONDUCTOR DEVICE

for which I/WE executed an application for United States Letters Patent concurrently herewith; or filed an application for United States Letters Patent on _____, (Serial No. _____); and

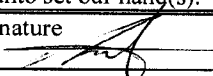
WHEREAS, MagnaChip Semiconductor, Ltd., a corporation of Republic of Korea, whose post office address is 1 Hyangjeong-dong, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea, (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention, the application for United States Letters Patent on this invention and the Letters Patent to be issue upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I/WE, as assignor(s), have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, MY/OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof; and I/WE hereby authorize and request the Commissioner of Patents and Trademarks of the United States to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, I/WE HEREBY further covenant and agree that I/WE will, without further consideration, communicate with assignee, its successors and assigns, any facts known to ME/US respecting this invention and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors and assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

AND, I/WE HEREBY authorize and request the attorneys I/WE have empowered in the Declaration and Power of Attorney in this application, to insert here in parentheses (Application No. 12/619,125, filed November 16, 2009) the filing date and application number of said application when known.

IN TESTIMONY WHEREOF, I/WE have hereunto set our hand(s).

Full Name of Sole or First Assignor LEE, Won-Kwon	Assignor's Signature 	Date October 30, 2009
Address: 1 Hyangjeong-dong, Heungduk-gu, Cheongju-si, Chungcheongbuk-do, 361-725, Republic of Korea		Citizenship Republic of Korea
Full Name of Second Assignor	Assignor's Signature	Date
Address:		Citizenship
Full Name of Third Assignor	Assignor's Signature	Date
Address:		Citizenship
Full Name of Fourth Assignor	Assignor's Signature	Date
Address		Citizenship
Names of additional inventors attached <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No		

Morgan, Lewis & Bockius LLP

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